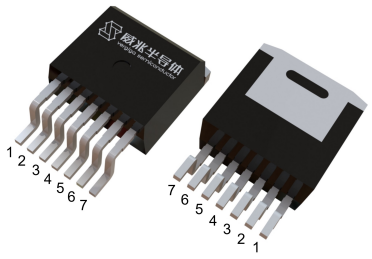
V_{DS}	1200	V
$R_{DS(on),TYP}$@ V_{GS}=20 V	80	mΩ
$I_{D(Silicon\ limited)}$	37	A

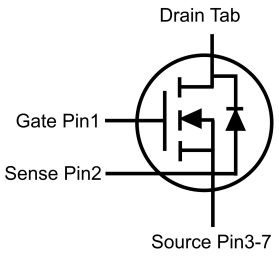
Features

- SiC MOSFET technology
- High blocking voltage with low on-resistance
- High-speed switching with low capacitances
- Very low switching losses
- Low reverse recovery (Qrr)
- 100% Avalanche tested,100% Rg tested

Pb-Free RoHS HF Halogen-Free

TO-263-7L





Part ID	Package Type	Marking	Packing
HCCC120R080H1	TO-263-7L	120R080H1	800pcs/Reel

Maximum ratings, at T_A =25°C, unless otherwise specified

Symbol	Parameter		Rating	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage		1200	V
V_{GSmax}	Gate-Source voltage (dynamic) AC (f >1 Hz) ①		-10/+25	V
V_{GSop}	Gate-Source voltage (static) ②		-5/+20	V
I_D	Continuous drain current @VGS=20V (Silicon limited)	T_C = 25°C	37	A
I_D	Continuous drain current @VGS=20V (Silicon limited)	T_C = 100°C	26	A
I_{DM}	Pulse drain current tested,VGS=20V ③	T_C = 25°C	96	A
EAS	Maximum avalanche energy, single pulsed ④		845	mJ
P_D	Maximum power dissipation ⑤	T_C = 25°C	221	W
		T_C = 100°C	110	W
T_{STG}	Storage temperature range		-55 to 150	°C
T_J	Operating junction temperature		-55 to 175	°C

Thermal Characteristics

Symbol	Parameter	Typical	Max	Unit
$R_{\theta JC}$	Thermal resistance, junction-to-case ⑥	0.57	0.68	°C/W
$R_{\theta JA}$	Thermal resistance, junction-to-ambient ⑦	50	60	°C/W

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ T_J=25°C (unless otherwise stated)						
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS}=0V, I_D=250μA	1200	--	--	V
I_{DSS}	Zero gate voltage drain current(Tj=25℃)	V_{DS}=1200V,V_{GS}=0V	--	--	50	μA
	Zero gate voltage drain current(Tj=125℃)⑧	V_{DS}=1000V,V_{GS}=0V	--	--	100	μA
I_{GSS}	Gate-body leakage current	V_{GS}=-5V,V_{DS}=0V	--	--	-100	nA
I_{GSS}	Gate-body leakage current	V_{GS}=20V,V_{DS}=0V	--	--	100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS}=V_{GS},I_D=5mA	1.8	2.8	4.5	V
$R_{DS(on)}$	Drain-source on-state resistance ⑨	V_{GS}=20V, I_D=20A	--	80	100	mΩ
		Tj=100℃ ⑧	--	96	--	mΩ
Dynamic Electrical Characteristics @ T_j = 25°C (unless otherwise stated)						
Ciss	Input capacitance ⑧	V_{DS}=800V,V_{GS}=0V, f=100kHz	--	1255	--	pF
Coss	Output capacitance ⑧		--	80	--	pF
Crss	Reverse transfer capacitance ⑧		--	5	--	pF
Rg	Gate resistance	f=1MHz	--	3.6	--	Ω
Qg	Total gate charge ⑧	V_{DS}=800V,I_D=20A, V_{GS}=-5/20V	--	58	--	nC
Qgs	Gate-source charge ⑧		--	21	--	nC
Qgd	Gate-drain charge ⑧		--	17	--	nC
Switching Characteristics ⑧						
Td(on)	Turn-on delay time	V_{DD}=800V, I_D=20A, R_G=2Ω, V_{GS}=-5/20V L=5.6mH (Fig17)	--	18	--	ns
Tr	Turn-on rise time		--	30	--	ns
Td(off)	Turn-off delay time		--	30	--	ns
Tf	Turn-off fall time		--	48	--	ns
Source- Drain Diode Characteristics@ T_j = 25°C (unless otherwise stated)						
V_{SD}	Forward on voltage	I_{SD}=10A,V_{GS}=-5V	--	3.9	6	V
Trr	Reverse recovery time ⑧	V_{DD}=800V I_{sd}=20A, V_{GS}=0V di/dt=500A/μs	--	16	--	ns
Qrr	Reverse recovery charge ⑧		--	39	--	nC
Irrm	Peak Reverse Recovery Current ⑧		--	4.3	--	A

NOTE:

① When using MOSFET Body Diode VGSmax = -10V/+25V

② MOSFET can also safely operate at -5/+20 V

③ Single pulse; pulse width limited by max junction temperature.

④ This maximum value is based on starting T_J = 25°C, L = 10mH, R_G = 25Ω, I_{AS} = 13A, V_{GS} =20V； 100% FT tested at L = 10mH, I_{AS} = 9A.

⑤ The power dissipation Pd is based on Tj(max), using junction-to-case thermal resistance RθJC.

⑥ Thermal resistance from junction to soldering point (on the exposed drain pad). These tests are performed on a cool plate.

⑦ The value of RθJA is measured with the device in a still air environment with TA =25°C.

⑧ Guaranteed by design, not subject to production testing.

⑨ Pulse width ≤ 380μs; duty cycle≤ 2%.

Typical Characteristics

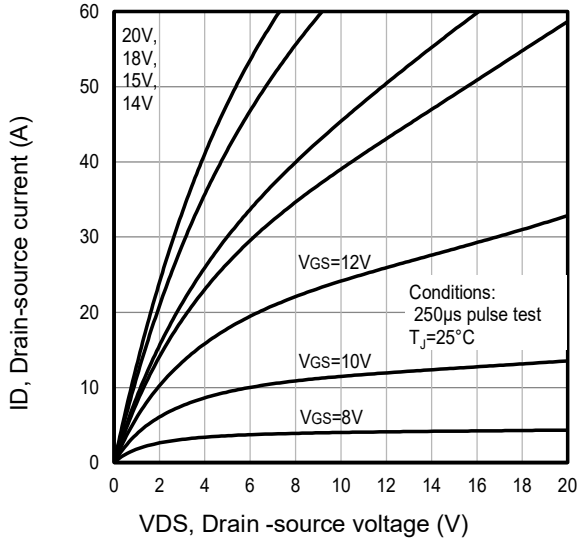


Fig1. Typical output characteristics

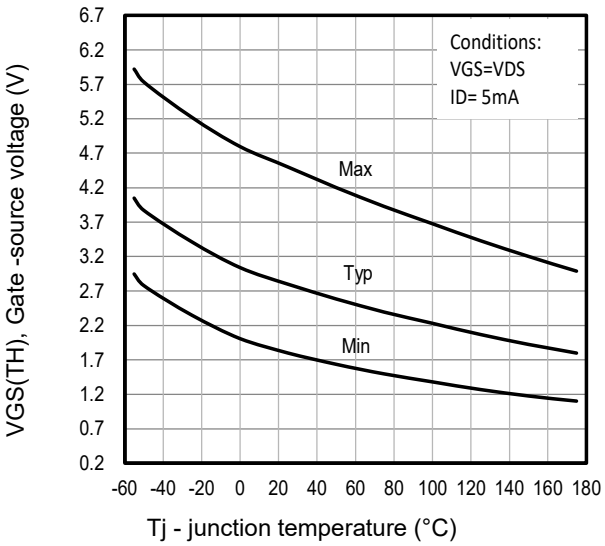


Fig2. Typical $V_{GS(TH)}$ gate -source voltage Vs. Tj

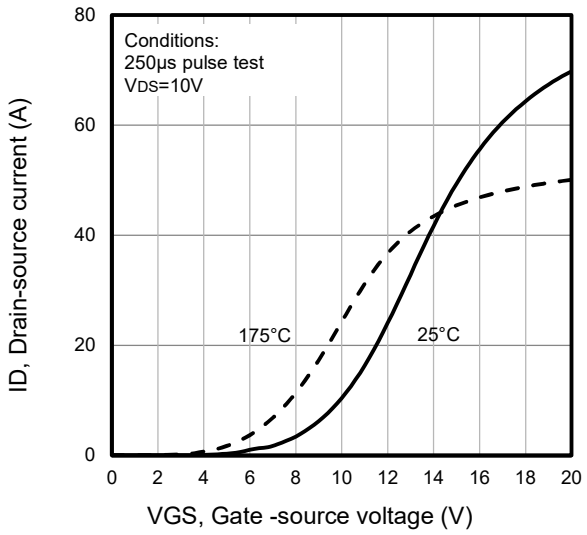


Fig3. Typical transfer characteristics

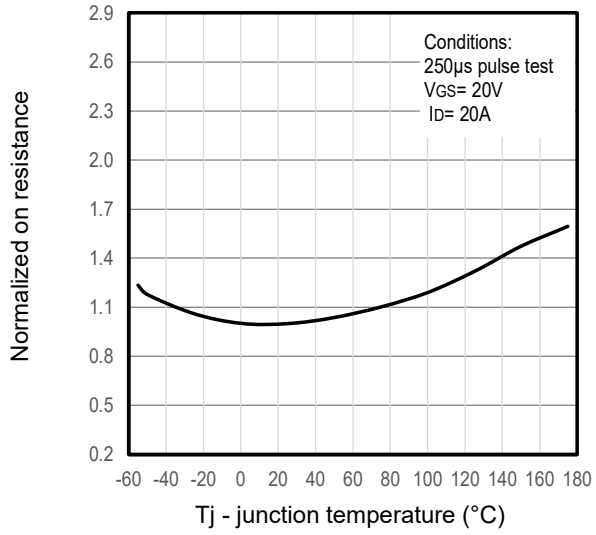


Fig4. Typical normalized on-resistance Vs. Tj

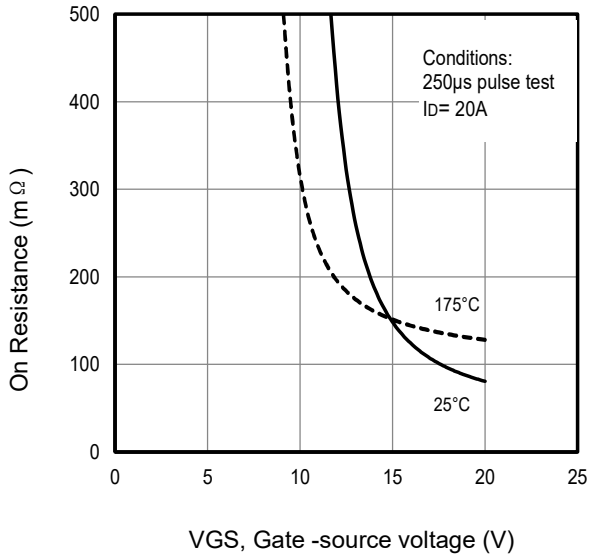


Fig5. Typical on resistance Vs gate -source voltage

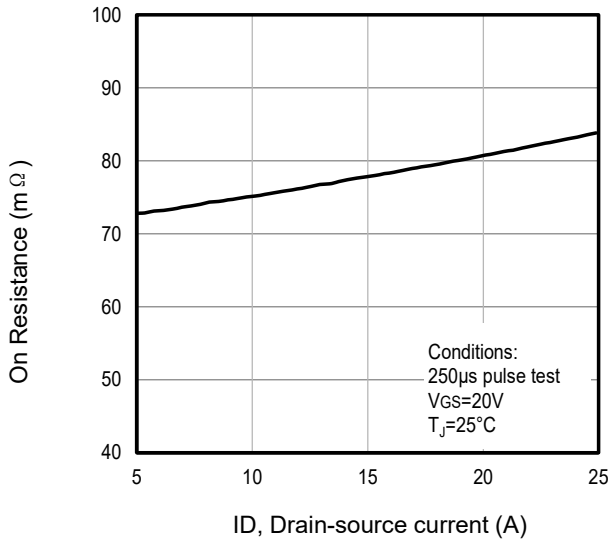


Fig6. Typical on resistance Vs drain current

Typical Characteristics

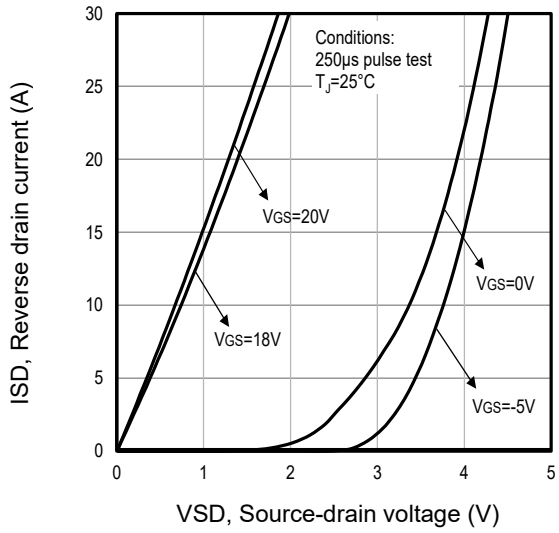


Fig7. Typical source-drain diode forward voltage

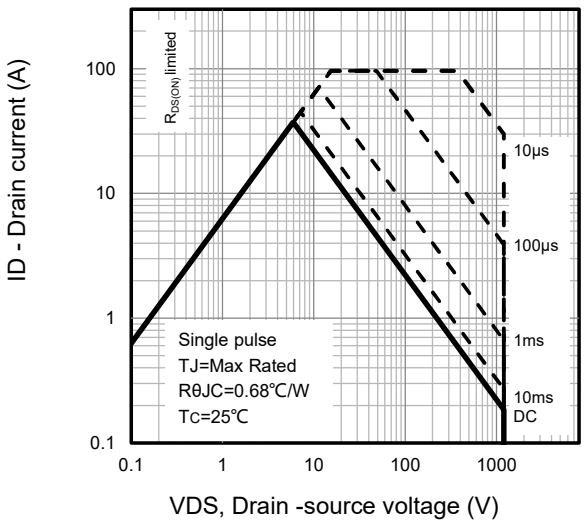


Fig8. Maximum safe operating area

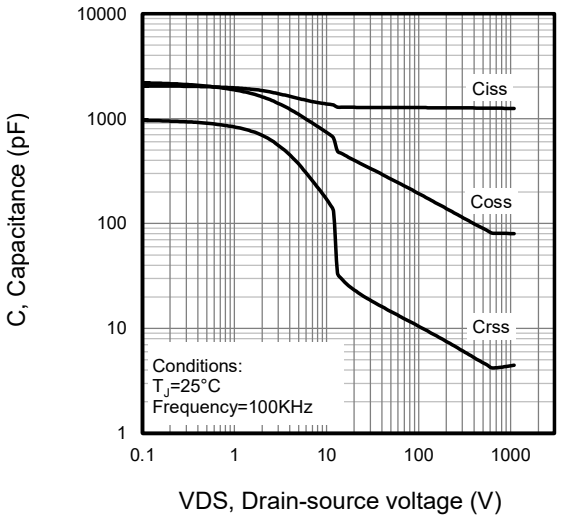


Fig9. Typical capacitance Vs. drain-source voltage

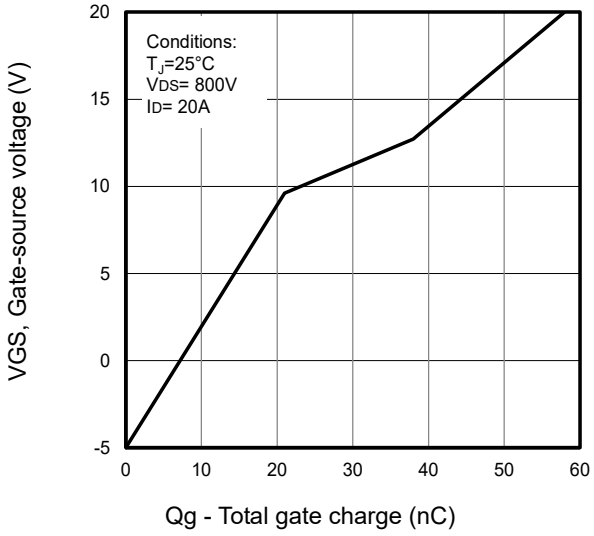


Fig10. Typical gate charge Vs. gate-source voltage

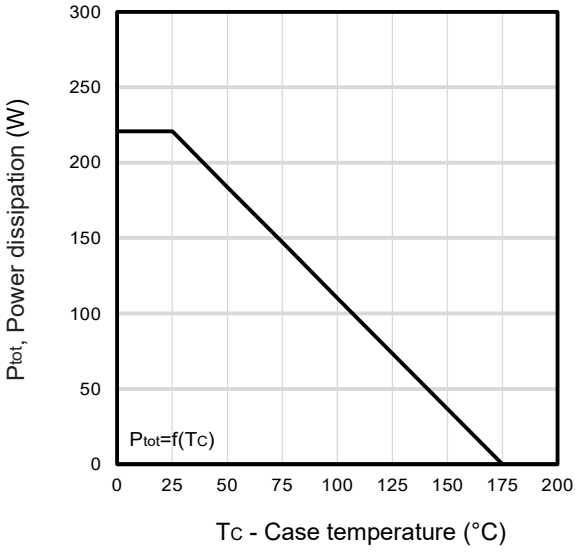


Fig11. Power dissipation Vs. case temperature

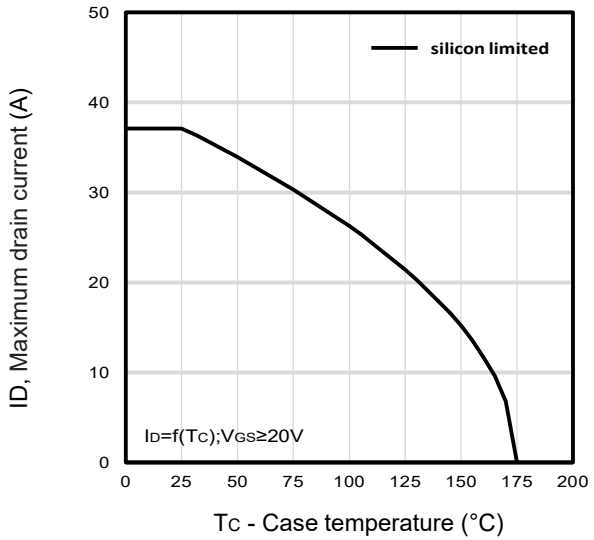


Fig12. Maximum drain current Vs. case temperature

Typical Characteristics

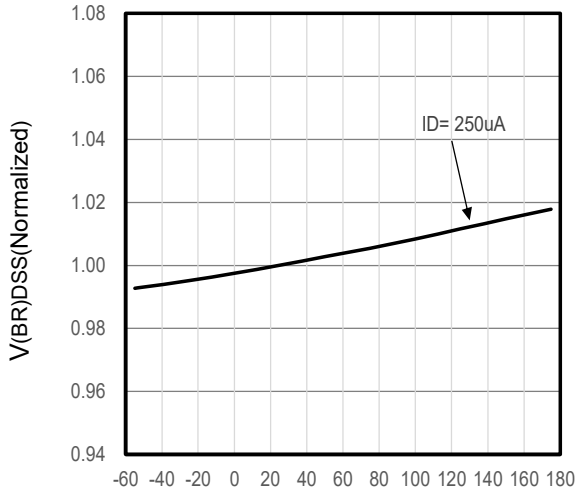


Fig13. Typical $V_{(BR)DSS}$ Vs Tj

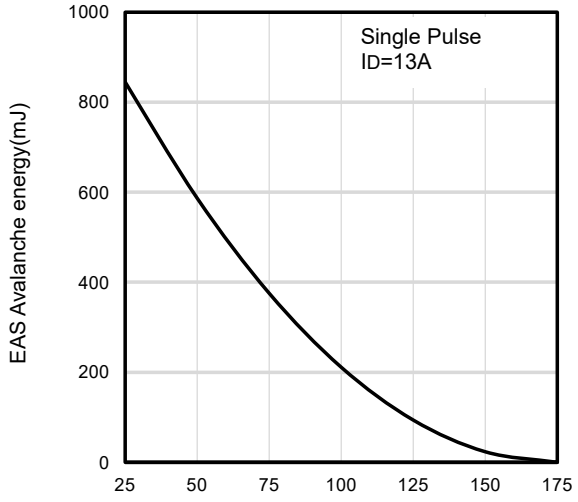


Fig14. Maximum avalanche energy vs temperature (°C)

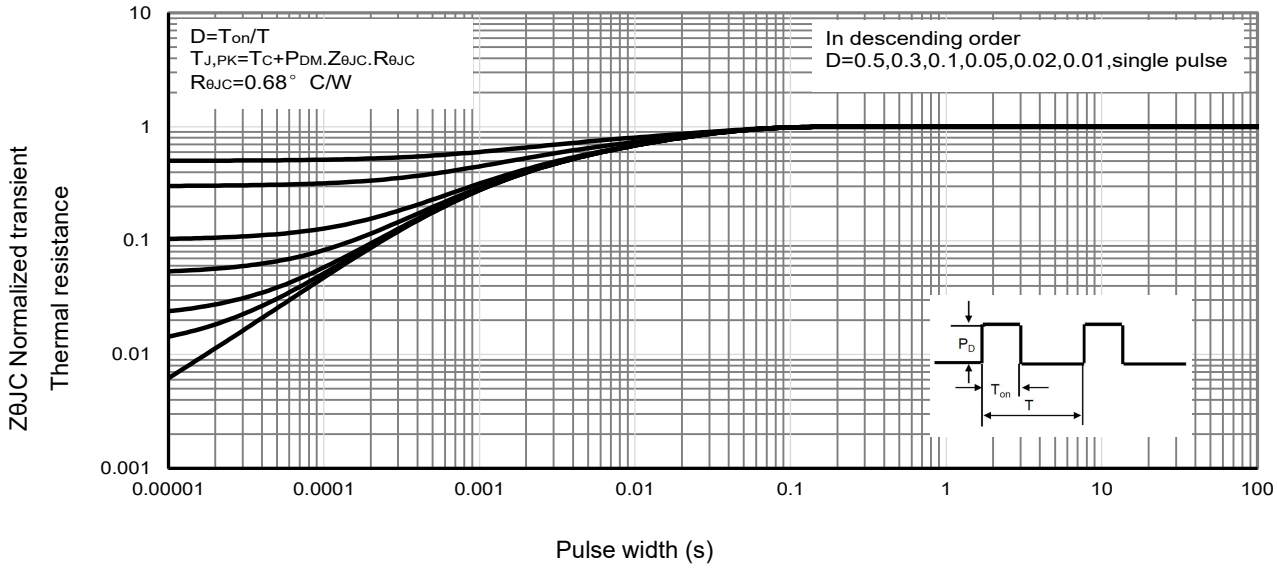


Fig15 . Normalized maximum transient thermal impedance

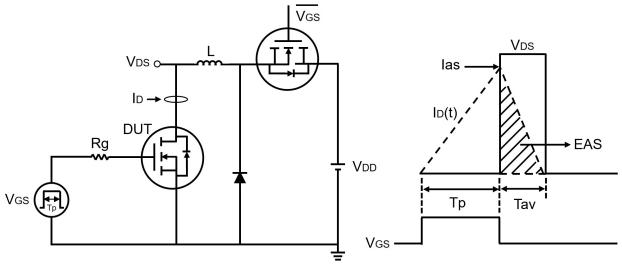


Fig16. Unclamped inductive test circuit and waveforms

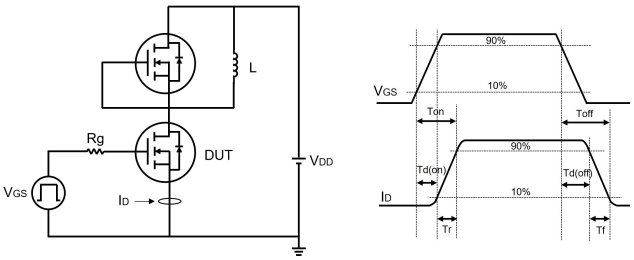
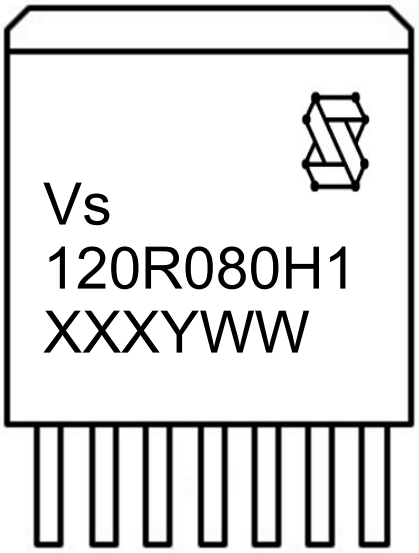


Fig17. Switching Energy Measurement Circuit

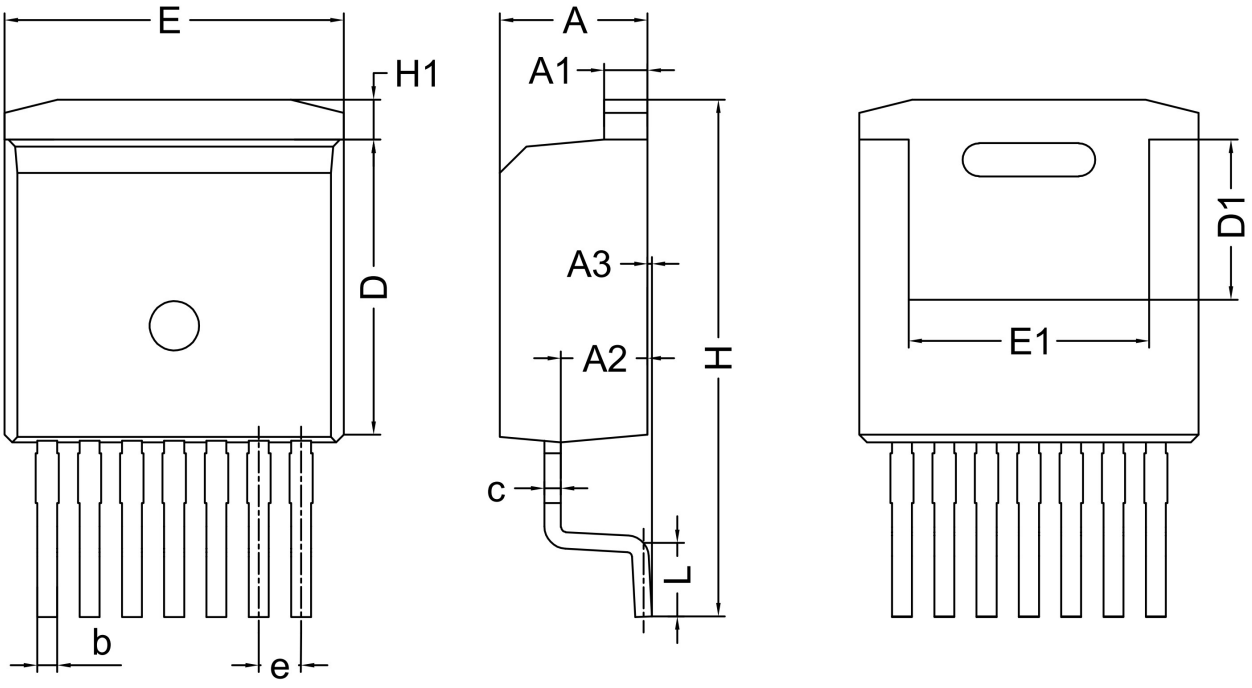
Marking Information



1st line: Vergiga Code（Vs）， Vergiga Logo
2nd line: Part Number（120R080H1）
3rd line: Date code （XXXYWW）
XXX: Wafer Lot Number Code , code changed with Lot Number
Y: Year Code ， refer to table below
WW: Week Code (01 to 53)

Code	C	D	E	F	G	H	J	K	L	M	N	P	Q	R	S	T
Year	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030

TO-263-7L Package Outline Data



Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	4.30	4.43	4.56
A1	1.20	1.30	1.40
A2	2.45	2.60	2.75
A3	0.00	0.13	0.25
b	0.50	0.60	0.70
c	0.45	0.50	0.60
D	8.93	9.08	9.23
D1	4.65	4.80	4.95
e	1.27 BSC		
E	10.08	10.18	10.28
E1	6.82	7.22	7.62
H	15.00	15.50	16.00
H1	0.98	1.20	1.42
L	1.90	2.20	2.50

Notes:

1. Dimension "D" & "E" do NOT include mold flash, mold flash shall not exceed 0.127mm per side.